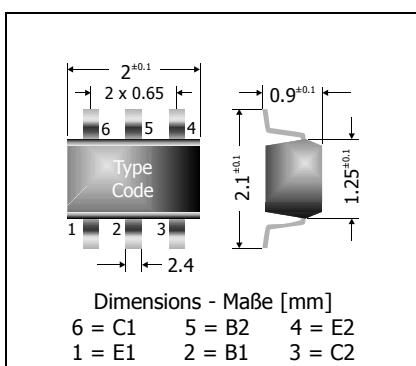


BC856S ... BC859S**PNP**
Surface Mount General Purpose Si-Epi-Planar Double-Transistors
Si-Epi-Planar Universal-Doppeltransistoren für die Oberflächenmontage
PNP

Version 2006-08-01



Power dissipation

300 mW

Verlustleistung

SOT-363

Plastic case

Kunststoffgehäuse

Weight approx. – Gewicht ca.

0.01 g

Plastic material has UL classification 94V-0
Gehäusematerial UL94V-0 klassifiziertStandard packaging taped and reeled
Standard Lieferform gegurtet auf Rolle**Maximum ratings ($T_A = 25^\circ\text{C}$)**

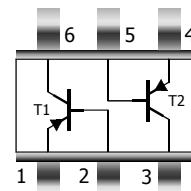
per transistor – pro Transistor		BC856S	BC857S	BC858S BC859S
Collector-Emitter-volt. – Kollektor-Emitter-Spannung B open	- V_{CBO}	65 V	45 V	30 V
Collector-Base-voltage – Kollektor-Basis-Spannung E open	- V_{CEO}	80 V	50 V	30 V
Emitter-Base-voltage – Emitter-Basis-Spannung C open	- V_{EBO}		5 V	
Power dissipation – Verlustleistung	P_{tot}		300 mW ¹⁾	
Collector current – Kollektorstrom (dc)	- I_C		100 mA	
Peak Collector current – Kollektor-Spitzenstrom	- I_{CM}		200 mA	
Peak Base current – Basis-Spitzenstrom	- I_{BM}		200 mA	
Peak Emitter current – Emitter-Spitzenstrom	I_{EM}		200 mA	
Junction temperature – Sperrsichttemperatur	T_j		-55...+150°C	
Storage temperature – Lagerungstemperatur	T_s		-55...+150°C	

Characteristics ($T_j = 25^\circ\text{C}$)

per transistor – pro Transistor		Min.	Typ.	Max.
DC current gain – Kollektor-Basis-Stromverhältnis				
- $V_{CE} = 5 \text{ V}$, - $I_C = 10 \mu\text{A}$	h_{FE}	–	90 ... 270	–
- $V_{CE} = 5 \text{ V}$, - $I_C = 2 \text{ mA}$	h_{FE}	110	–	800
h-Parameters at/bei - $V_{CE} = 5 \text{ V}$, - $I_C = 2 \text{ mA}$, f = 1 kHz				
Small signal current gain – Kleinsignal-Stromverstärkung	h_{fe}	–	220 ... 600	–
Input impedance – Eingangs-Impedanz	h_{ie}	1.6 kΩ	–	15 kΩ
Output admittance – Ausgangs-Leitwert	h_{oe}	18 μS	–	110 μS
Reverser voltage transfer ratio – Spannungsrückwirkung	h_{re}	–	1.5 ... 3*10 ⁻⁴	–

1 Mounted on P.C. board with 3 mm² copper pad at each terminal
Montage auf Leiterplatte mit 3 mm² Kupferbelag (Lötpad) an jedem Anschluss

Characteristics ($T_j = 25^\circ\text{C}$)Kennwerte ($T_j = 25^\circ\text{C}$)

per transistor – pro Transistor		Min.	Typ.	Max.			
Collector-Emitter saturation voltage – Kollektor-Sättigungsspannung ²⁾							
- $I_C = 10 \text{ mA}$, - $I_B = 0.5 \text{ mA}$	- V_{CEsat}	–	90 mV	250 mV			
- $I_C = 100 \text{ mA}$, - $I_B = 5 \text{ mA}$	- V_{CEsat}	–	200 mV	600 mV			
Base-Emitter saturation voltage – Basis-Sättigungsspannung ²⁾							
- $I_C = 10 \text{ mA}$, - $I_B = 0.5 \text{ mA}$	- V_{BEsat}	–	700 mV	–			
- $I_C = 100 \text{ mA}$, - $I_B = 5 \text{ mA}$	- V_{BEsat}	–	900 mV	–			
Base-Emitter-voltage – Basis-Emitter-Spannung ²⁾							
- $V_{CE} = 5 \text{ V}$, - $I_C = 2 \text{ mA}$	- V_{BE}	600 mV	650 mV	750 mV			
- $V_{CE} = 5 \text{ V}$, - $I_C = 10 \text{ mA}$	- V_{BE}	–	–	820 mV			
Collector-Base cutoff current – Kollektor-Basis-Reststrom							
- $V_{CB} = 30 \text{ V}$, (E open)	- I_{CBO}	–	–	15 nA			
- $V_{CE} = 30 \text{ V}$, $T_j = 125^\circ\text{C}$, (E open)	- I_{CBO}	–	–	5 μA			
Emitter-Base cutoff current							
- $V_{EB} = 5 \text{ V}$, (C open)	- I_{EBO}	–	–	100 nA			
Gain-Bandwidth Product – Transitfrequenz							
- $V_{CE} = 5 \text{ V}$, - $I_C = 10 \text{ mA}$, $f = 100 \text{ MHz}$	f_T	100 MHz	–	–			
Collector-Base Capacitance – Kollektor-Basis-Kapazität							
- $V_{CB} = 10 \text{ V}$, $I_E = i_e = 0$, $f = 1 \text{ MHz}$	C_{CBO}	–	–	6 pF			
Emitter-Base Capacitance – Emitter-Basis-Kapazität							
- $V_{EB} = 0.5 \text{ V}$, $I_C = i_c = 0$, $f = 1 \text{ MHz}$	C_{EBO}	–	10 pF	–			
Thermal resistance junction to ambient air Wärmewiderstand Sperrsicht – umgebende Luft	R_{thA}	< 420 K/W ¹⁾					
Recommended complementary NPN transistors Empfohlene komplementäre NPN-Transistoren	BC846S ... BC849S						
Pinning – Anschlussbelegung							
	T1: E1 = 1, C1 = 6, B1 = 2 T2: E2 = 4, C2 = 3, B2 = 5						

2 Tested with pulses $t_p = 300 \mu\text{s}$, duty cycle $\leq 2\%$ – Gemessen mit Impulsen $t_p = 300 \mu\text{s}$, Schaltverhältnis $\leq 2\%$

1 Mounted on P.C. board with 3 mm^2 copper pad at each terminal
Montage auf Leiterplatte mit 3 mm^2 Kupferbelag (Lötpad) an jedem Anschluss